

## H5N2901FN

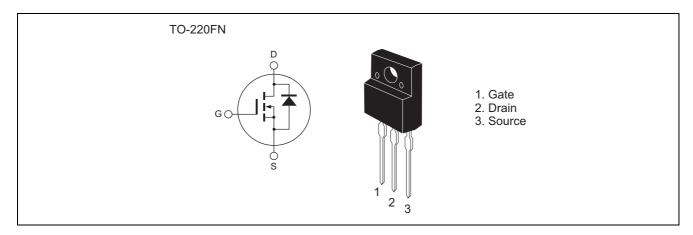
# Silicon N Channel MOS FET High Speed Power Switching

REJ03G0372-0100Z Rev.1.00 May.28.2004

#### **Features**

- Low on-resistance
- Low leakage current
- High speed switching

#### **Outline**



#### **Absolute Maximum Ratings**

 $(Ta = 25^{\circ}C)$ 

Item	Symbol	Ratings	Unit
Drain to Source voltage	V <sub>DSS</sub>	290	V
Gate to Source voltage	$V_{GSS}$	±30	V
Drain current	I <sub>D</sub>	18	A
Drain peak current	I <sub>D (pulse)</sub> Note1	72	A
Body-Drain diode reverse Drain current	I <sub>DR</sub>	18	A
Body-Drain diode reverse Drain peak current	I <sub>DR (pulse)</sub> Note1	72	A
Avalanche current	I <sub>AP</sub> Note3	6	A
Avalanche energy	E <sub>AR</sub> Note3	2.1	mJ
Channel dissipation	Pch Note2	30	W
Channel to case thermal impedance	θch-c	4.17	°C/W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55 to +150	°C

Notes: 1. PW  $\leq$  10  $\mu$ s, duty cycle  $\leq$  1%

- 2. Value at Tc = 25°C
- 3. STch =  $25^{\circ}$ C, Tch  $\leq 150^{\circ}$ C

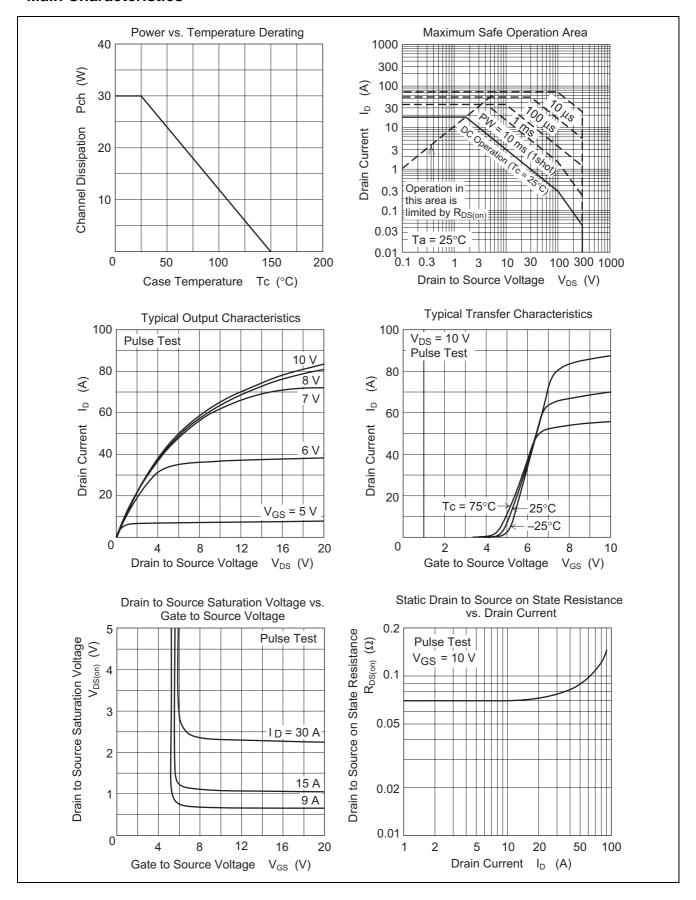
## **Electrical Characteristics**

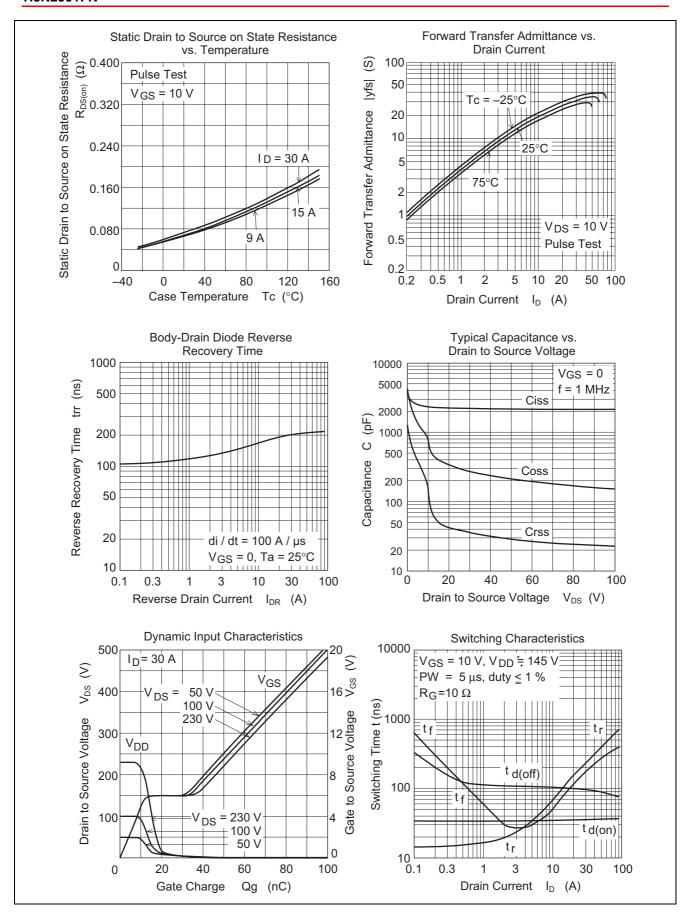
 $(Ta = 25^{\circ}C)$ 

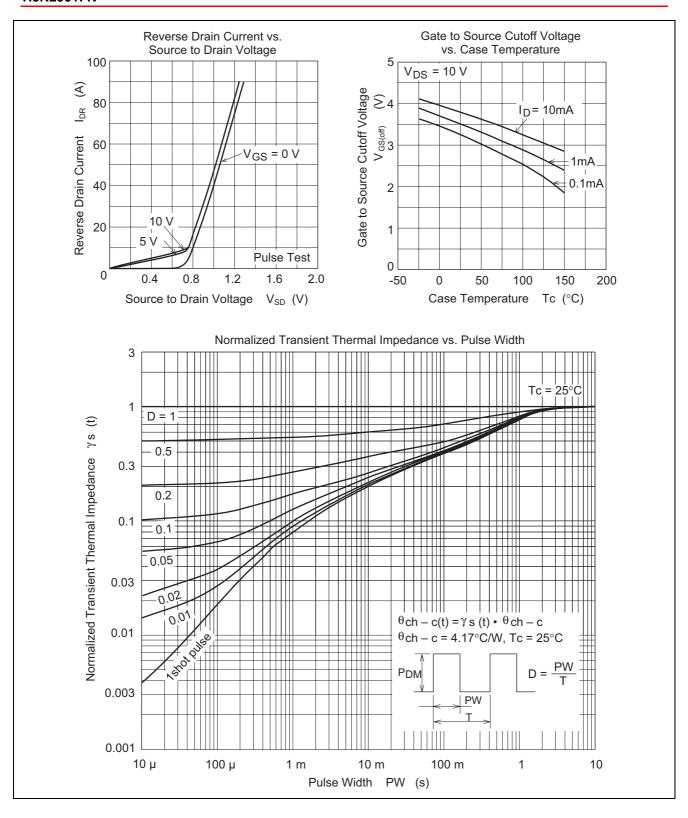
Item	Symbol	Min	Тур	Max	Unit	Test conditions
Drain to Source breakdown voltage	$V_{(BR)DSS}$	290	_	_	V	$I_D = 10 \text{ mA}, V_{GS} = 0$
Zero Gate voltage drain current	I <sub>DSS</sub>	_	_	1	μΑ	$V_{DS} = 290 \text{ V}, V_{GS} = 0$
Gate to Source leak current	I <sub>GSS</sub>	_	_	±0.1	μΑ	$V_{GS} = \pm 30 \text{ V}, V_{DS} = 0$
Gate to Source cutoff voltage	V <sub>GS(off)</sub>	3.0	_	4.0	٧	$V_{DS} = 10 \text{ V}, I_{D} = 1 \text{ mA}$
Forward transfer admittance	yfs	10	18	_	S	$I_D = 9 \text{ A}, V_{DS} = 10 \text{ V}^{\text{Note4}}$
Static Drain to Source on state resistance	R <sub>DS(on)</sub>	_	0.070	0.091	Ω	$I_D = 9 \text{ A}, V_{GS} = 10 \text{ V}^{\text{Note4}}$
Input capacitance	Ciss	_	2200	_	pF	V <sub>DS</sub> = 25 V
Output capacitance	Coss	_	300	_	pF	V <sub>GS</sub> = 0 f = 1 MHz
Reverse transfer capacitance	Crss	_	38	_	pF	
Turn-on delay time	td(on)	_	35	_	ns	I <sub>D</sub> = 9 A
Rise time	tr	_	60	_	ns	$V_{GS} = 10 \text{ V}$ $R_L = 16.1 \Omega$ $Rg = 10 \Omega$
Turn-off delay time	td(off)	_	110	_	ns	
Fall time	tf	_	45	_	ns	
Total Gate charge	Qg	_	56	_	nC	V <sub>DD</sub> = 230 V
Gate to Source charge	Qgs	_	13	_	nC	V <sub>GS</sub> = 10 V I <sub>D</sub> = 18 A
Gate to Drain charge	Qgd	_	26	_	nC	
Body-Drain diode forward voltage	$V_{DF}$	_	0.9	1.5	V	$I_F = 18 \text{ A}, V_{GS} = 0^{\text{Note4}}$
Body-Drain diode reverse recovery time	trr	_	190	_	ns	$I_F = 18 \text{ A}, V_{GS} = 0$ diF/dt = 100 A/ $\mu$ s
Body-Drain diode reverse recovery charge	Qrr	_	1.3	_	μС	

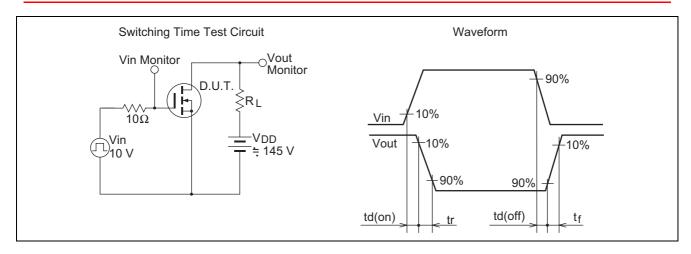
Notes: 4. Pulse test

#### **Main Characteristics**

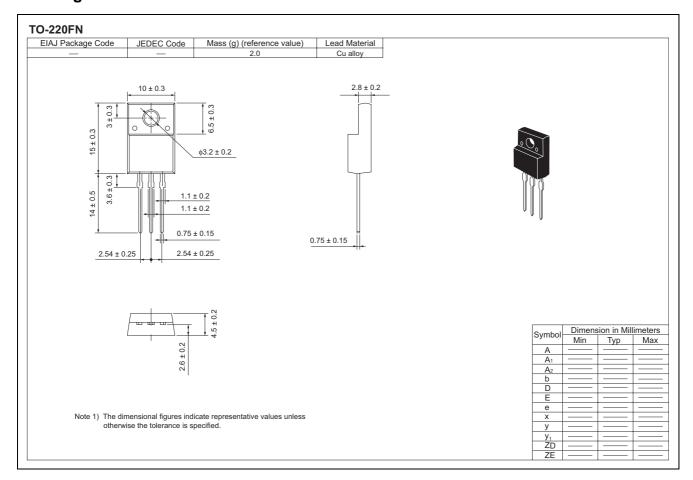








## **Package Dimensions**



## **Ordering Information**

Part Name	Quantity	Shipping Container
H5N2901FN-E	50 pcs	Plastic magazine

Note: For some grades, production may be terminated. Please contact the Renesas sales office to check the state of production before ordering the product.

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